CFP2 Terminal Pins: Straight Actuator Color: Gray

Ultra-Miniature Pushbutton Switches

Washable



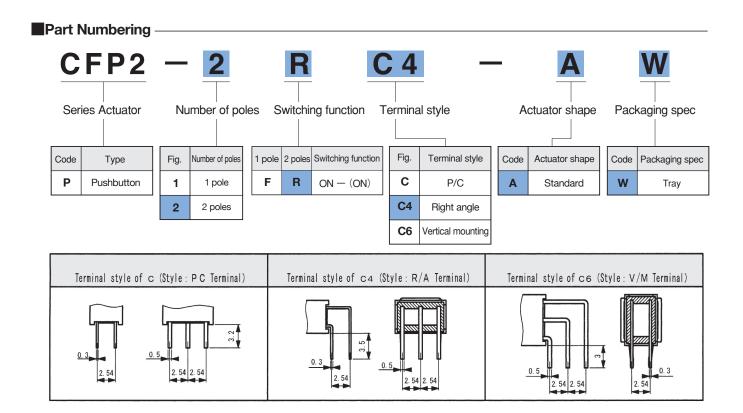
RoHS Compliant

Features -

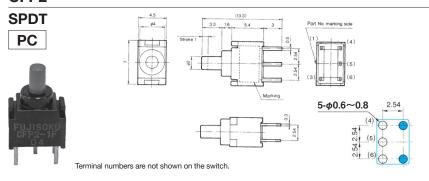
- 1. Ultra-miniature pushbutton switch for high density mounting.
- 2. Washable.
- 3. Terminal pin pitch: 2.54 mm.
- 4. Independent detent mechanism ensures light operational feel.
- 5. Clip contact mechanism for long-term contact reliability.
- 6. Gold-plated contacts.

■ Specifications

Rating	Max.	0.4VA (28VDC ma	x.)
	Min.	1μA 20mVDC	
Initial contact resistance		100m Ω max.	(1.5mA 200µVAC)
Dielectric strength		250VAC 1 minute	
Insulation resistance		500MΩ min. (250VDC)	
Electrical life		10,000 operations at max.rating, 30,000 operations at min.rating,	
Mechanical life		30,000 cycles	
Operating force		1.47±0.98N	
Operating temperature range		-40~+85°C	
Storage temperature range		-40~+85°C	

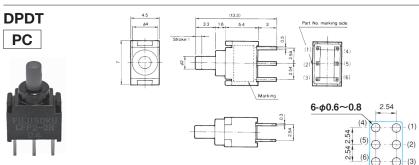


CFP2



Switching function Part No.	1	±
CFP2-1FC-AW	ON	(ON)
Connecting terminals	5-6	5-4

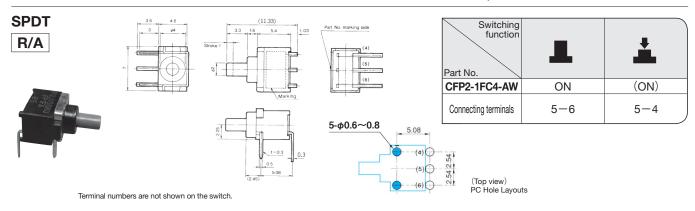
(Top view) PC Hole Layouts

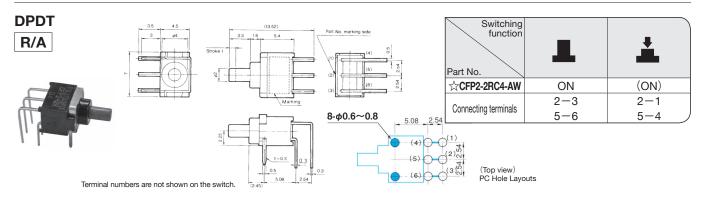


Switching function Part No.	1	*
☆CFP2-2RC-AW	ON	(ON)
Connecting terminals	2-3	2-1
Connecting terminals	5-6	5-4

Terminal numbers are not shown on the switch.

(Top view) PC Hole Layouts



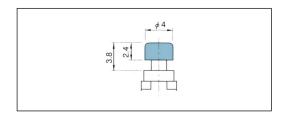


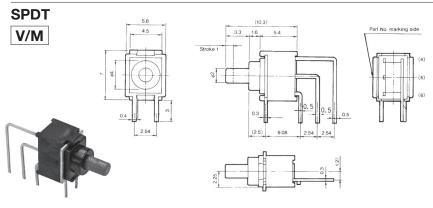
^{*} The above PC Hole Layouts are top view drawings.

Optional Accessories

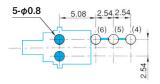
			《Sold separately》
Part Name	Dimension	Color	Part Number
	Gloss finish	White	140000481453
Color Cap	 • 4 	Red	140000481452
Color Cap		Black	140000481451
	ABS resin	Gray	140000481450

■ Color Cap Mounting



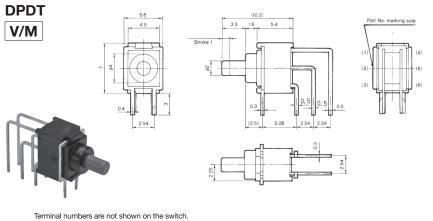


Switching function Part No.	T	±
CFP2-1FC6-AW	ON	(ON)
Connecting terminals	5-6	5-4

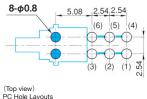


(Top view) PC Hole Layouts

Terminal numbers are not shown on the switch



Switching function Part No.		<u></u>
☆CFP2-2RC6-AW	ON	(ON)
Connecting terminals	2-3 5-6	2-1 5-4



* The above pcb hole dimengion, it is a top view drawling when we fix the switch.

■Handling Specifications (CFP2)

1. Soldering Specifications

(1)Manual Soldering

Device: Soldering iron

350°C, Max.; 3 seconds, Max.

(2)Auto Soldering

Device: Jet wave type or dip type

260°C, Max.; 3-5 seconds, Max. (One time)

Total dip time: Within 10 seconds

- Pre-heating should be done at temperatures from 80°C to 120°C and within 120 seconds
- (3)When soldering two or more terminals to a common land, use solder resist to separate them

2. Flux Cleaning

- (1)Solvents: Fluorine or Alcohol type
- (2) Cleaning after soldering should be done after the PC board is exposed to room temperature (30°C or below) for 1 to 2 hours.
- (3)Do not use ultrasonic cleaning.

■ Packaging Specifications

